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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yutaka Kobayashi

Serial No.: 09/893,791

Group Art Unit: 2815

Filed: June 29, 2001

Examiner: Chu, Chris C.

For: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING SAME

Honorable Assistant Commissioner of Patents
Washington, D.C. 20231

AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated **April 8, 2002**, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 5-13 without prejudice or disclaimer.

Please amend the following claims:

1. (Amended) A semiconductor device, comprising:

- a semiconductor chip;
- a chip-mounting substrate which is provided with said semiconductor chip mounted on a top surface thereof and first conductive pads formed on a bottom surface thereof and connected with said semiconductor chip electrically;
- solder balls formed on said first conductive pads;
- a printed circuit board on which second conductive pads connected with said solder balls are formed; and
- material injected into a clearance formed between said chip-mounting substrate and said printed circuit board,

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